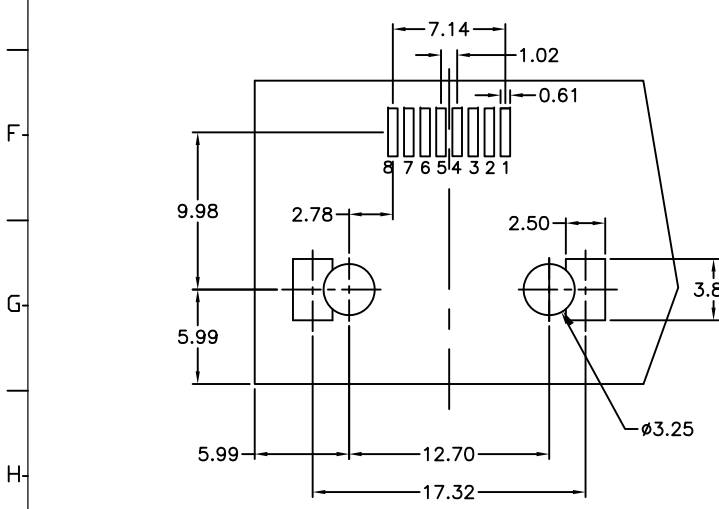
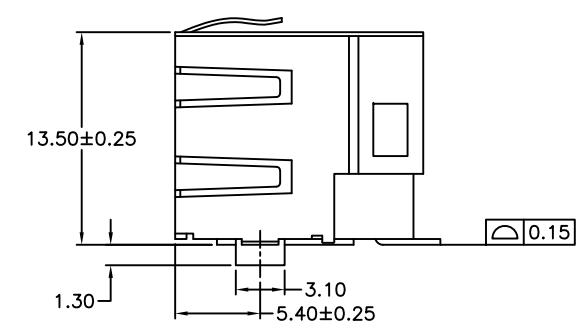
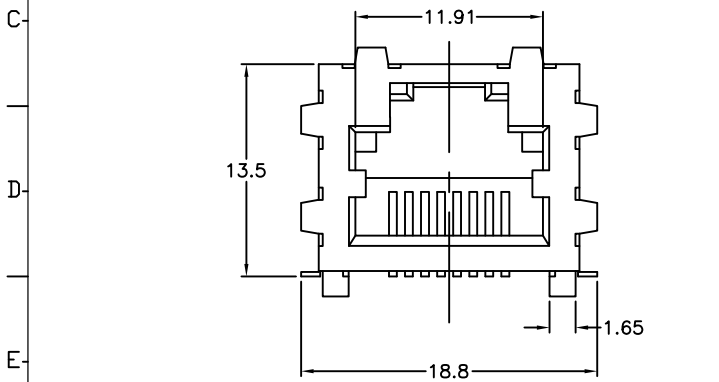
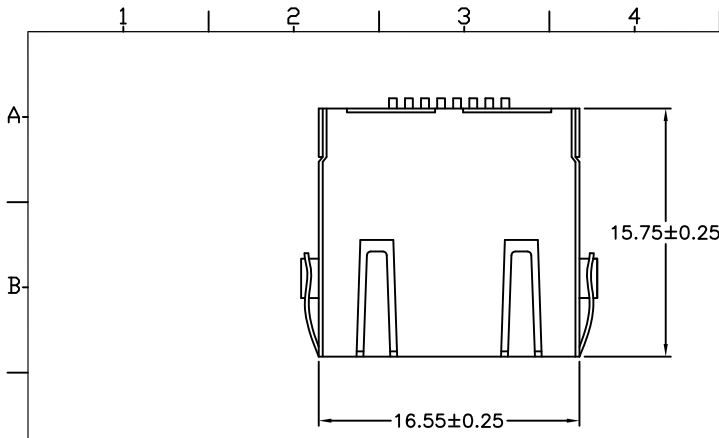
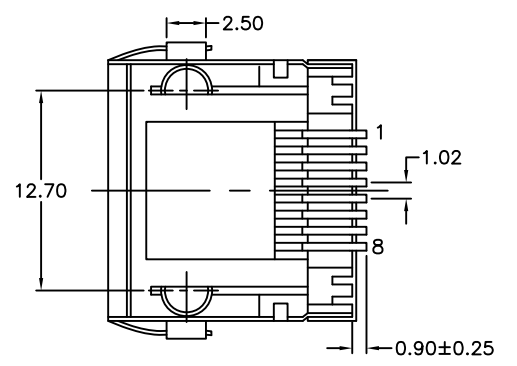


REV.	SPECIFICATION	ECN NO.	APPD.



P.C. Board Layout



8949-L1D 8 8 1 -06 S 1 B A

Series ——— 8949-L1D
8:8 Position ——— 8 8
8: 8 Contacts ——— 1
6: 6 Contacts ——— -06
4: 4 Contacts ——— S
2: 2 Contacts ——— 1
1: 1 Port ——— B A

A: Tray Package
T: Tape&Reel Package
B: Black
0: W/O Grounding
1: With Grounding
S: Shield
06: 6μ" Gold Plated
15: 15μ" Gold Plated
30: 30μ" Gold Plated
50: 50μ" Gold Plated

Material:
Housing: PA9T, 30% Glass Filled, UL94V-0, Black.
Insert: PA46, 30% Glass Filled, UL94V-0, Black.
Contact: Phosphor Bronze, Gold Plated on Contact Area and Gold Flash Solder Tail over Nickel 50μ".
Shell: Brass.

Electrical Characteristics:
Current Rating: 1.5 AMP.
Dielectric Withstanding Voltage: 1000V for 1 minute.
Insulator Resistance: 500MΩ min. at DC 500V.
Contact Resistance: 20mΩ max, at 100mA.
Operating Temperature: -40°C~+85°C.
***RoHS Compliant**

Tolerances	Dwg. No.	8949D02160	Title:	
x = ±0.50	Projection		8949-L1D Series	
.x = ±0.25	Unit	mm	Scale	1:1
.xx = ±0.15	Drawn By	Vic Lyu02/22'16	Modular Jack W/O LED	

① 563

OUPIN			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 8949-L1D881-06S1BA			
SHEET	1/1	Ver.No.	A2